



100V N-Channel MOSFETs

General Description

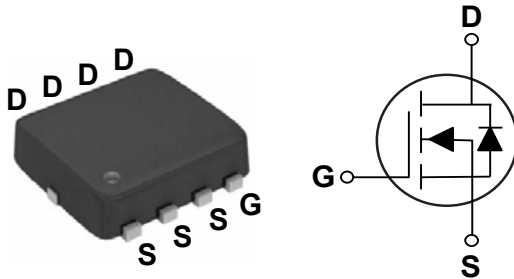
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
100 V	14.4 mΩ	48 A

Features

- $R_{DS(ON)} \leq 14.4m\Omega @ V_{GS}=10V$
- Improved dv/dt Capability
- Fast Switching
- Green Device Available

PPAK3X3 Pin Configuration



Applications

- Networking
- Load Switch
- LED applications

Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	+20 / -12	V
I_D	Drain Current - Continuous ($T_C=25^\circ C$)	48	A
	Drain Current - Continuous ($T_C=100^\circ C$)	30	A
I_{DM}	Drain Current - Pulsed (NOTE 1)	61	A
EAS	Single Pulse Avalanche Energy (NOTE 2)	16.2	mJ
IAS	Single Pulse Avalanche Current (NOTE 2)	18	A
P_D	Power Dissipation ($T_C=25^\circ C$)	61	W
	Power Dissipation - Derate above $25^\circ C$	0.49	W/ $^\circ C$
T_J	Operating Junction Temperature Range	-50 to 150	$^\circ C$
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ C$
Marking Code		NM014 , DC0982	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.04	$^\circ C/W$

**Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V, T _J =25°C	---	---	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =+20V, V _{DS} =0V	---	---	100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =15A	---	---	14.4	mΩ
		V _{GS} =4.5V, I _D =10A	---	---	26	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	---	3.0	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =3A	---	8	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =10V, I _D =12A (NOTE 3 · 4)	---	22.5	---	nC
Q _{gs}	Gate-Source Charge		---	5.29	---	
Q _{gd}	Gate-Drain Charge		---	5.28	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =50V, V _{GS} =10V, R _G =3Ω, I _D =1A (NOTE 3 · 4)	---	8.6	---	nS
T _r	Rise Time		---	3.6	---	
T _{d(off)}	Turn-Off Delay Time		---	22.6	---	
T _f	Fall Time		---	67.2	---	
C _{iss}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, F=1MHz	---	1227	---	pF
C _{oss}	Output Capacitance		---	382	---	
C _{rss}	Reverse Transfer Capacitance		---	30	---	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	0.9	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	48	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time (NOTE 3)	I _S =10A, dI/dt=100A/us, T _J =25°C	---	43.5	---	nS
Q _{rr}	Reverse Recovery Charge (NOTE 3)		---	59.6	---	nC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=50V, L=0.1mH, I_{AS}=18A, Starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



Characteristics Curves

FIG. 1 - Drain Current vs. T_C

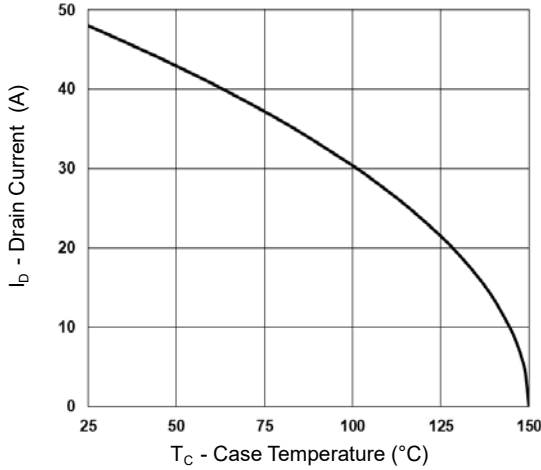


FIG. 2 - Normalized $R_{DS(on)}$ vs. T_J

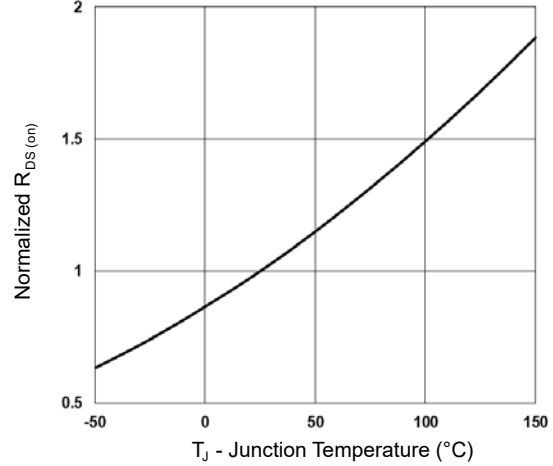


FIG. 3 - Normalized V_{th} vs. T_J

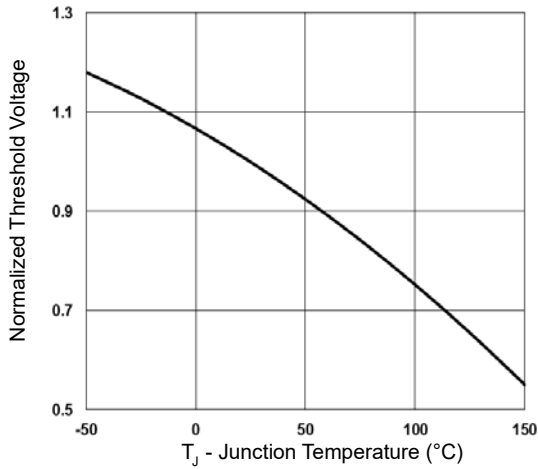


FIG. 4 - Gate Charge Characteristics

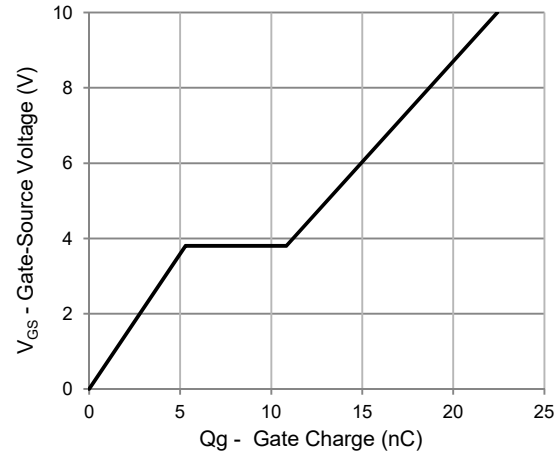


FIG. 5 - Safe Operating Area

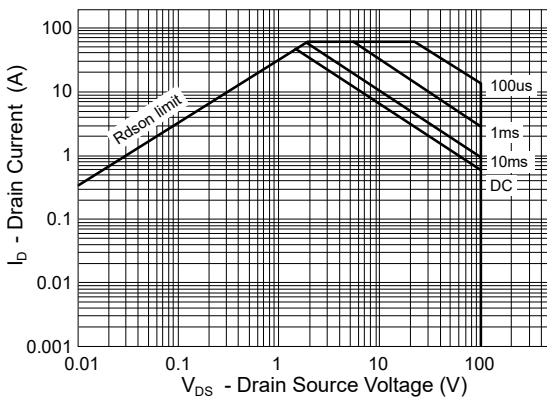
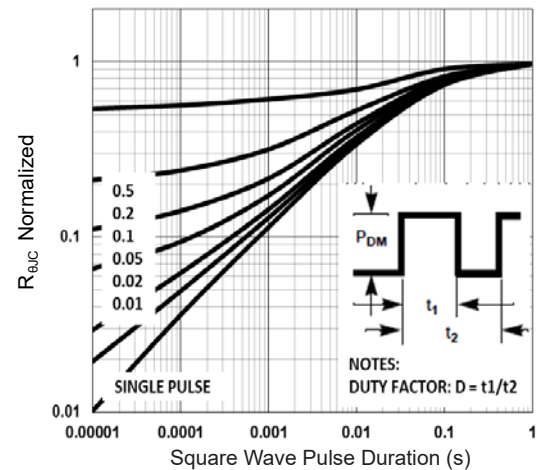


FIG. 6 - Normalized Transient Impedance





Characteristics Curves

FIG. 7 - Gate Charge Waveform

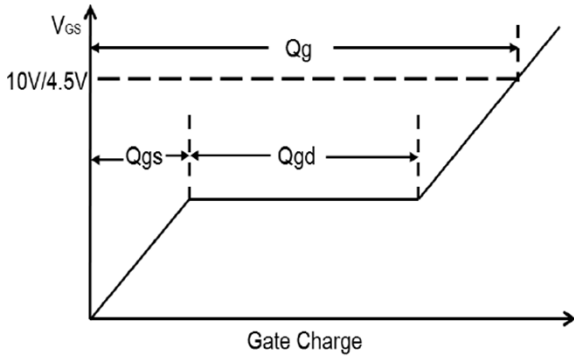
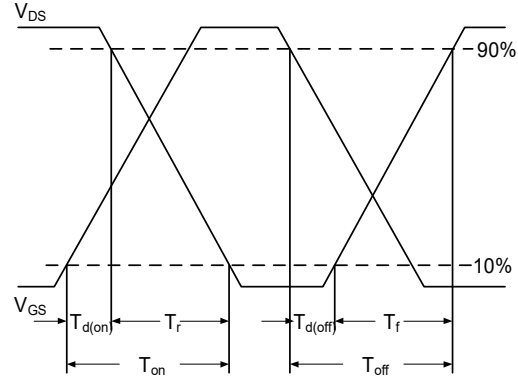
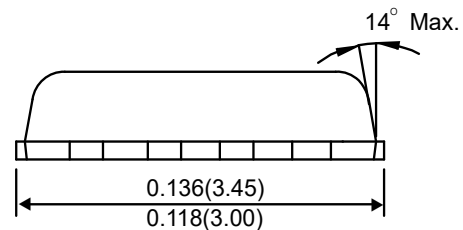
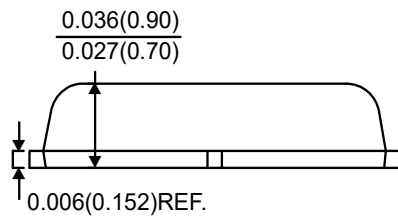
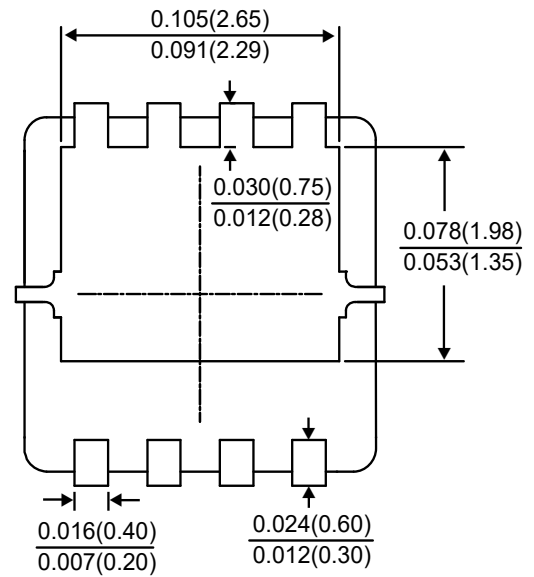
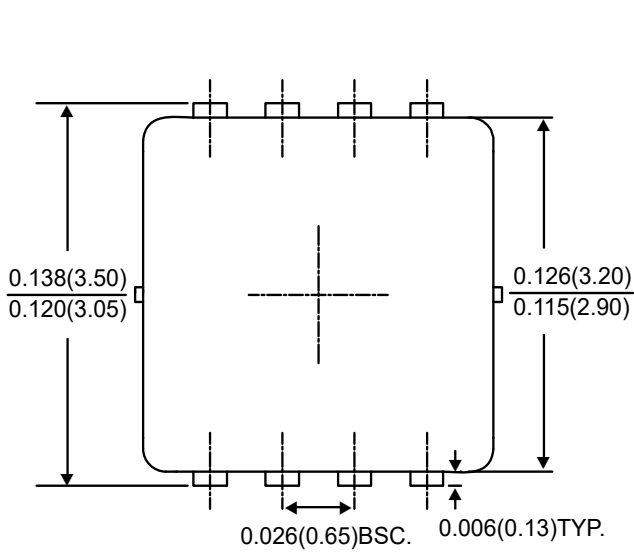


FIG. 8 - Switching Time Waveform



Package Outline Dimensions



PPAK3X3

Dimensions in inches and (millimeters)



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